

WHAT IS CLAIMED IS:

1. An electronic device comprising:
  - a package having a metal part shaped by pressing
  - 5 a metal member, and an insulator part bonded to the metal part through fusing;
  - a chip housed in the package;
  - first terminals electrically connected to the chip and buried in the insulator part so as to be
  - 10 arranged in a line; and
  - a plate member that supports the chip from a backside thereof,
  - the metal parts having recess portions that define second external terminals,
  - 15 the plate member being provided so as to cover the recess portions.
2. The electronic device as claimed in claim 1, wherein:
  - 20 the first external terminals are arranged in a line along a first side of the package; and
  - the second external terminals are arranged in a line along a second side of the package opposite to the first side.
- 25 3. The electronic device as claimed in claim 1, wherein the recess portions, the insulator part and the first terminals form a surface of the electronic device.
- 30 4. The electronic device as claimed in claim 1, wherein the plate member is attached to the metal part.
- 35 5. The electronic device as claimed in claim 1, wherein the backside of the chip is attached to the plate member.

6. The electronic device as claimed in claim 1, wherein the plate member is a metal member.

5           7. The electronic device as claimed in claim 1, wherein the metal part has through holes in which the insulator part is provided.

8. The electronic device as claimed in claim 10 1, wherein:

the first terminals have parts to which metal wires are attached for making connections with terminals of the chip; and

the parts of the first terminals being flush 15 with the terminals of the chip.

9. The electronic device as claimed in claim 1, wherein the first and second external terminals have a symmetrical arrangement. 20

10. The electronic device as claimed in claim 1, wherein the first and second external terminals have an asymmetrical arrangement.

25           11. The electronic device as claimed in claim 1, wherein the first external terminals have contact areas that are identical to or different from those of the second external terminals.

30           12. The electronic device as claimed in claim 1, wherein the second external terminals are ground terminals and are not connected to the chip.

13. The electronic device as claimed in claim 35 1, wherein the insulator part comprises glass.

14. The electronic device as claimed in claim

1, wherein the chip is a surface acoustic wave chip.

15. The electronic device as claimed in claim 1, wherein:

5 the package has a flange that is a part of the metal part; and

the electronic device further comprises a cap attached to the flange.

10 16. An electronic device comprising:

a package having a metal part shaped by pressing a metal member, and an insulator part bonded to the metal part through fusing;

a chip housed in the package;

15 first terminals electrically connected to the chip and buried in the insulator part so as to be arranged in a line; and

second terminals attached to an outer surface of the metal part,

20 the chip being attached to an inner surface of the metal surface and facing the second external terminals through the metal part.

17. The electronic device as claimed in claim 25 16, wherein the second external terminals are partially buried in the insulator part.

18. The electronic device as claimed in claim 30 16, wherein the second external terminals are partially located on the insulator part.

19. The electronic device as claimed in claim 16, wherein the second external terminals are parts of a single-piece member.

35

20. The electronic device as claimed in claim 16, wherein the second external terminals are welded to

the metal part.

21. A package comprising:  
a metal part shaped by pressing a metal member;  
5 an insulator part bonded to the metal part  
through fusing;  
first terminals electrically connected to a chip  
and buried in the insulator part so as to be arranged  
in a line; and  
10 a plate member that supports the chip from a  
backside thereof,  
the metal parts having recess portions that  
define second external terminals,  
the plate member being provided so as to cover  
15 the recess portions.

22. A package comprising:  
a metal part shaped by pressing a metal member;  
an insulator part bonded to the metal part  
20 through fusing;  
first terminals electrically connected to a chip  
and buried in the insulator part so as to be arranged  
in a line; and  
second terminals attached to an outer surface of  
25 the metal part,  
the chip being attached to an inner surface of  
the metal surface and facing the second external  
terminals through the metal part.